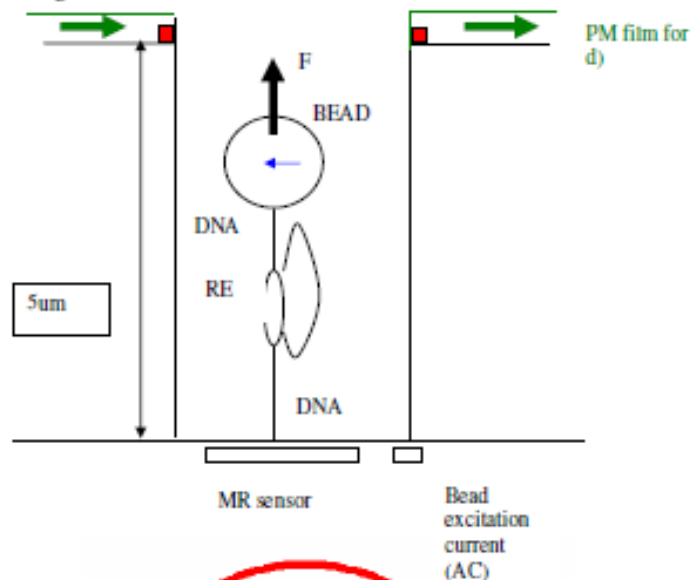


ANNEX 1

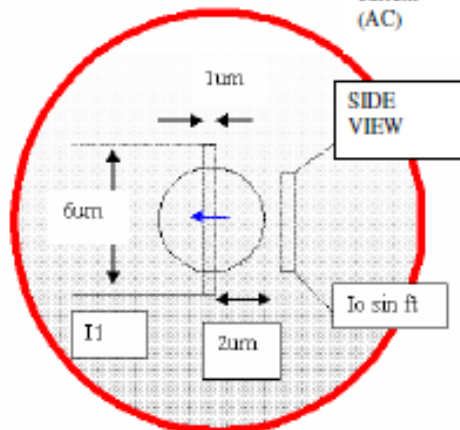
3 problems from the nanoelectronics course at IST-Lisbon

Problem 1

“Dimensioning a magnetic tweezer and a sensor to monitor DNA translocation using an restriction enzyme molecular motor”
Consider Fig.1



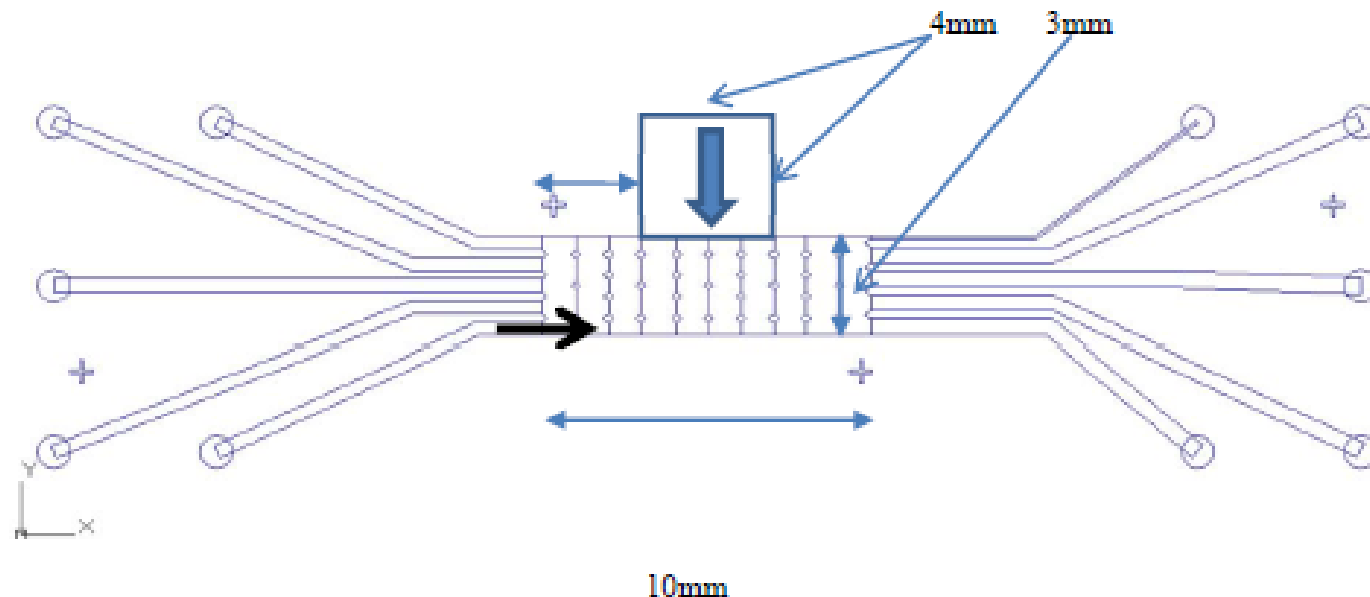
- a) The Magnetic Tweezer. Calculate the force F_z that the 1 μm radius bead (susceptibility $\chi=0.5$, for $H < 2\text{ kA/m}$) will be subject to, created by the field B_z caused by the current loop ($I = 50\text{ mA}$, $R=10\mu\text{m}$). The loop is placed on a oxide mesa, $5\mu\text{m}$ thick. The bead attaches to a DNA strand, $2\mu\text{m}$ long.
- b) Now redesign the magnetic tweezer using a thin, magnetized CoPt film, 100nm thick ($M_r=400\text{ kA/m}$), placed on top of the $5\mu\text{m}$ thick oxide. For the field calculation, consider only the magnet extremities at the border of the pit, and use a 2D approach (magnet width $\gg$ magnet thickness). Calculate the force created by this magnet on the bead.
- $H_n = -(\sigma/2\pi) (\theta_2 - \theta_1)$; $H_t = -(\sigma/2\pi) \ln(r_2/r_1)$ (see class, where σ is the magnetic surface charge $M \cdot n$).
- c) Now the bead is magnetized by an AC field created by a current wire on the substrate ($I = 40\text{ mA} \sin 100\text{ Hz } t$) Assuming the susceptibility given above, calculate the rms voltage in the magnetoresistive sensor created by the bead, at its initial separation. The magnetoresistive sensor is a spin valve, with a maximum $MR=10\%$, a resistance per square $R=200\Omega/\text{sq}$, dimensions ($6\mu\text{m}$ by $2\mu\text{m}$), with a DC bias current of 10 mA , and a linear range of $\pm 1\text{ kA/m}$. Calculate the spatial sensitivity ($\text{del V}/\text{del Z}$) around the initial bead position.



Problem 3: a biomolecular separation lab on chip platform (scheduled handing in time: October 16th 2012)

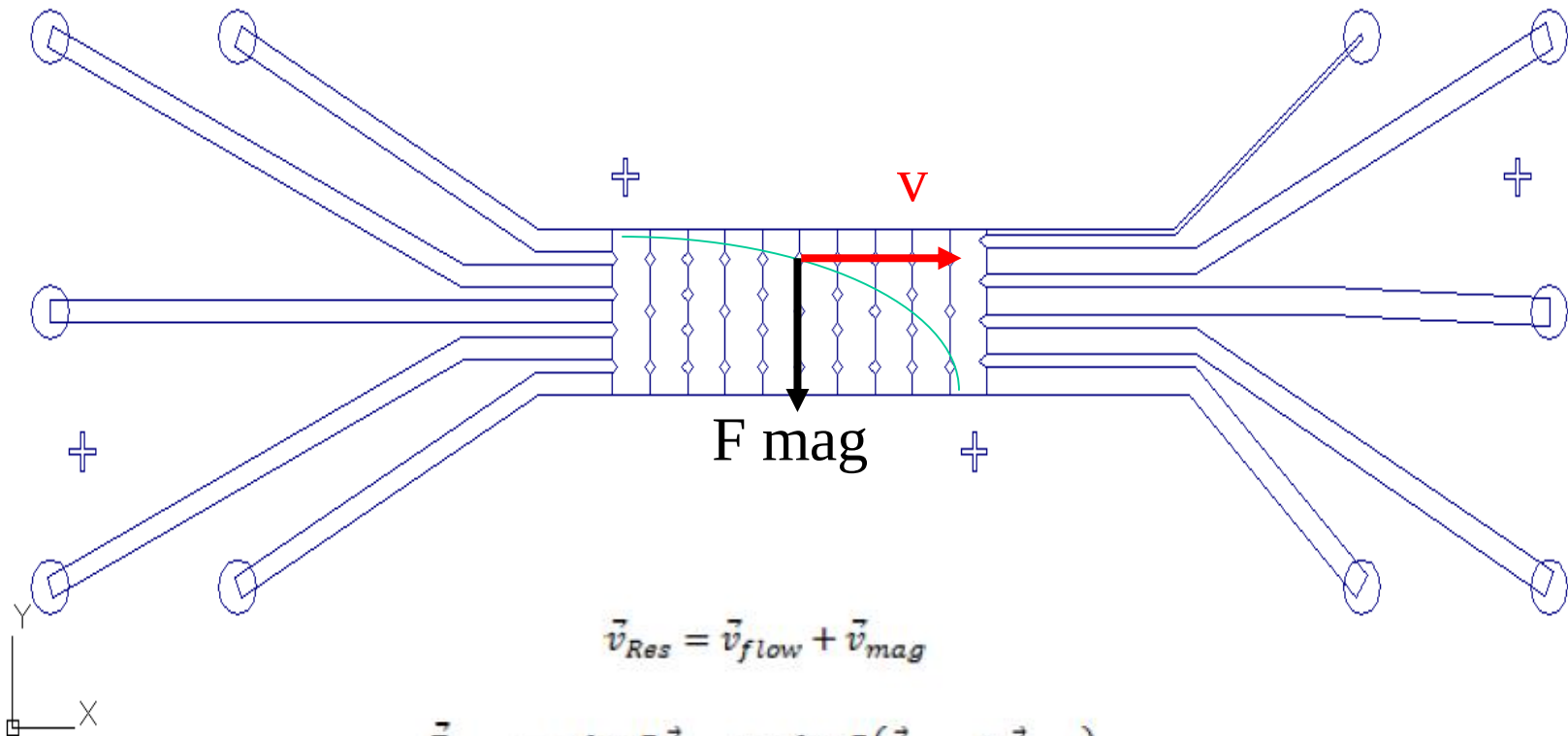
Fig.1 shows a top view of a microfluidic chamber used for biomolecular separation. The chamber is 14 μm high, 10mm long and 3mm wide. Cells labeled with magnetic nanoparticles enter from the left bottom inlet, with a horizontal velocity of 1, 5 and 10 mm/s (fluid velocity) and are subject to the magnetic force created by a permanent magnet placed as indicated in the figure ($M_r = 1100 \text{ kA/m}$, magnet dimensions $4 \times 4 \text{ mm}^2$). Calculate the cell trajectory neglecting gravity and impulsion forces (only the Stokes force $F_{\text{drag}} = 6 \pi R \mu (v_{\text{fluid}} - v_{\text{bead}})$ and the magnetic force $F_b = \text{grad} (\mathbf{m} \cdot \mathbf{B})$ will affect the bead motion, where $R_b = 1.0 \mu\text{m}$, and $\mu = 0.001 \text{ Pa s}$). Assume that the cell coated with magnetic nanoparticles acts as a macro moment with saturation magnetization $M_s = 57 \text{ kA/m}$, for $H > 500 \text{ kA/m}$ (magnetic susceptibility $\chi = 0.25$ for $H < H_s = 500 \text{ kA/m}$), and moment $\mathbf{m} = M_s V \mathbf{b}$. Calculate the bead trajectory for a bead that enters at the bottom for different horizontal fluid velocities of 1, 5 and 10 mm/s.

Note: in practice assume that for a time intervals Δt the bead almost immediately reaches the terminal speed given where $F_{\text{mag}} + F_{\text{drag}} = 0$ and use this terminal speed to calculate the motion within this time interval. Take into account both horizontal and vertical field gradients created by the magnet on the bead. For the horizontal movement take also into account the magnetic force along x.



Magnetophoresis: using magnetic beads to separate biological entities

$$F_{\text{mag}} = \nabla (m \cdot B)$$



$$\vec{v}_{Res} = \vec{v}_{flow} + \vec{v}_{mag}$$

$$\vec{F}_{drag} = -6\pi\eta R \vec{v}_{res} = -6\pi\eta R (\vec{v}_{flow} + \vec{v}_{mag})$$

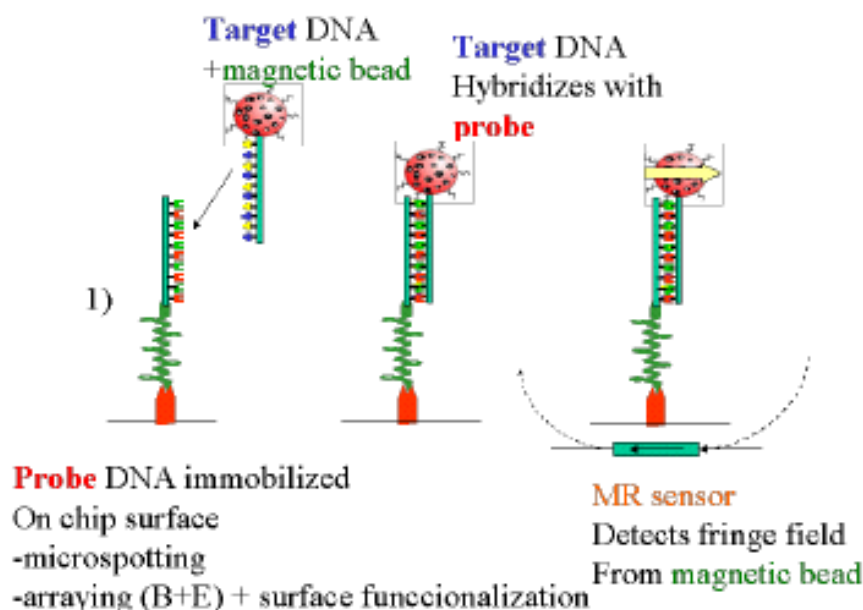
$$v_{mag} = \frac{F_{mag}}{F_{dragx}} = \frac{\mu_0 m}{6\pi\eta R} \nabla H$$

Problem 4: A magnetoresistive based biochip for biomolecular recognition detection.
(to be handed in Tuesday October 30th)

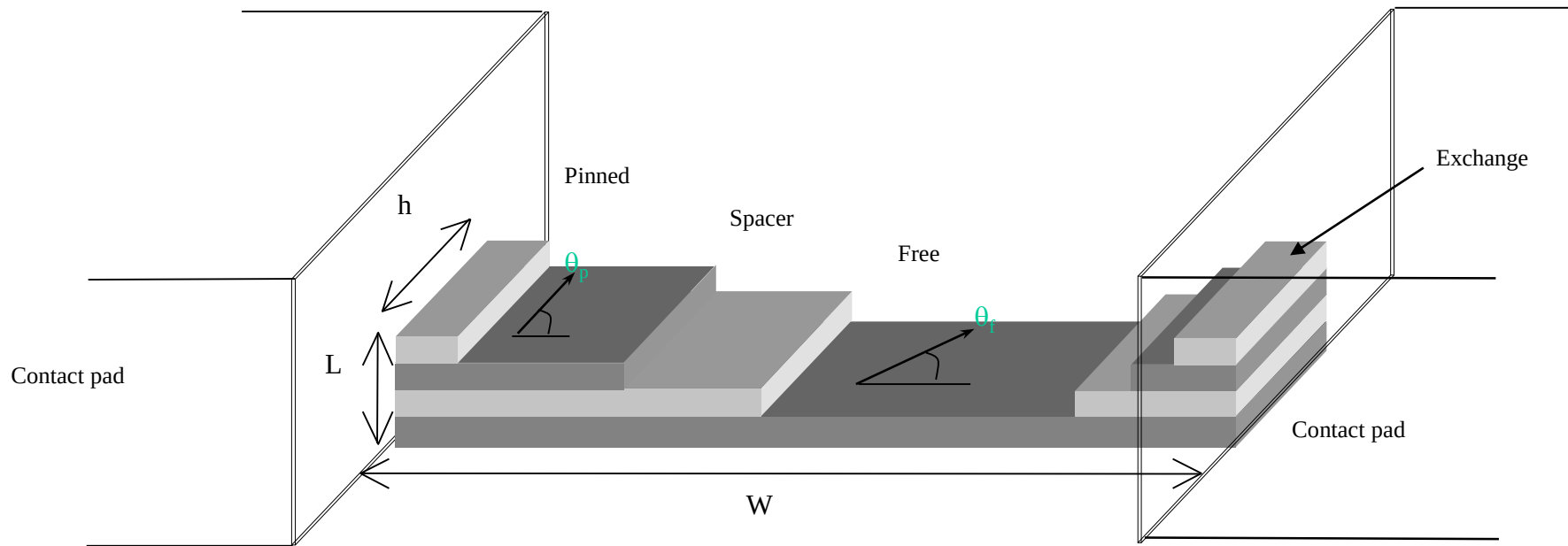
In a biomolecular recognition chip, probes are immobilized on a substrate, and labeled targets are arrayed over the probes. When complementarity exists between the probe and target, the target biomolecule becomes immobilized on the substrate, and the label can be detected by an integrated transducer. A magnetoresistive biochip uses a magnetoresistive detector to measure the fringe field coming from magnetic labels attached to biomolecular targets, that are specifically bound to immobilized probes. In this problem consider that target DNA is labeled with magnetic nanoparticles (magnetite based) with a diameter of 100nm and a magnetic susceptibility at low frequency (< 1 kHz) of 1. The labels are magnetized by a transverse AC field of 1kA/m (amplitude) at 800 Hz created by integrated Helmholtz coils. The label fringe field is detected with a linearized spin valve sensor with dimensions $2\mu\text{m} \times 80\mu\text{m}$, with $MR = 10\%$, $H_k^{\text{eff}} = 1.5\text{kA/m}$, $R_s = 1\text{k}\Omega$, $I_s = 2\text{mA}$. The spin valve sensor is passivated by a AlOx layer 400nm thick.

- Calculate the response of the sensor to a single bead fringe field, assuming the bead is placed over the center of the sensor. Assume the bead center to sensor free layer separation to be 400nm.
- Knowing that the sensor noise level at 800 Hz is $50\text{nV}/\sqrt{\text{Hz}}$ calculate the minimum number of these labels that can be detected by this sensor. Assume that a frequency bandwidth of 100 Hz is used for the measurement, and that the beads are located approximately near the center line of the sensor (away from the edges).

$$\Delta V(\text{SV}) = MR \cdot R_s \cdot I_s \cdot \langle H_s \rangle / 2H_k^{\text{eff}}$$



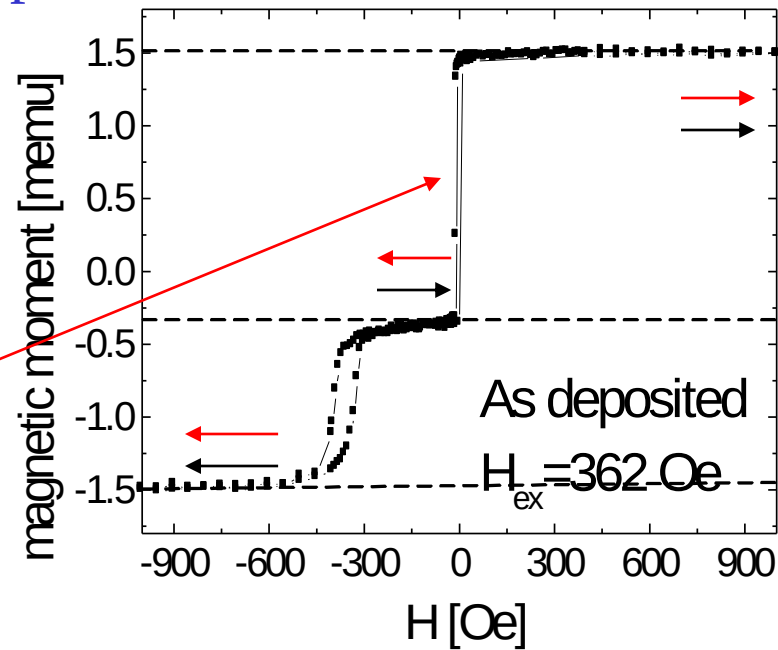
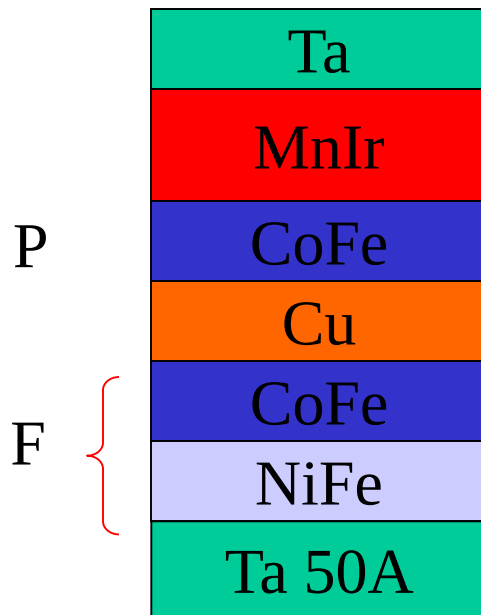
ANNEX II: The Spin Valve Sensor



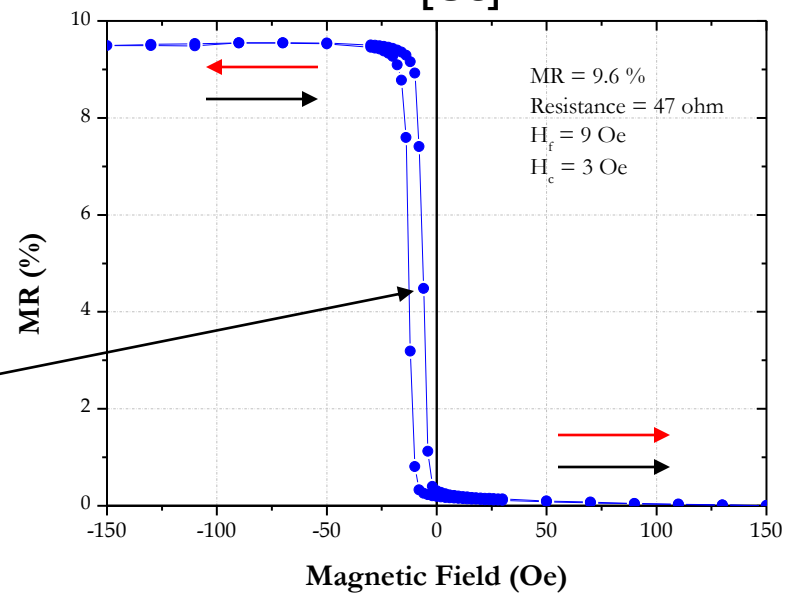
$$\Delta V = \frac{1}{2} (\Delta R/R) \cdot I \cdot R_{sq} \cdot (W/h) \langle 1 - \cos(\theta_f - \theta_p) \rangle$$

- 1- C.Tsang, R.E.Fontana, T.Lin, D.E.Heim, V.S.Speriosu, B.A.Gurney, and M.L.Williams, IEEE Trans.Magn., 30, 3801 (1994).
- 3- B.Dieny, V.S.Speriosu, S.S.Parkin, B.A.Gurney, D.R.Wilhoit, and D.Mauri, Phys.Rev.B, 43, 1297(1991).
- 4- D.E.Heim, R.E.Fontana, C.Tsang, V.S.Speriosu, B.A.Gurney, and M.L.Williams, IEEE Trans.Magn., 30, 316 (1994); P.P.Freitas, J.L.Leal, L.V.Melo, N.J.Oliveira, L.Rodrigues, and A.T.Sousa, Appl.Phys.Lett., 65, 493 (1994);
J.L.Leal, N.J.Oliveira, L.Rodrigues, A.T.Sousa, and P.P.Freitas, IEEE Trans.Magn., 30, 3031(1994).

ANNEX-II Spin Valve sensors-magnetic response

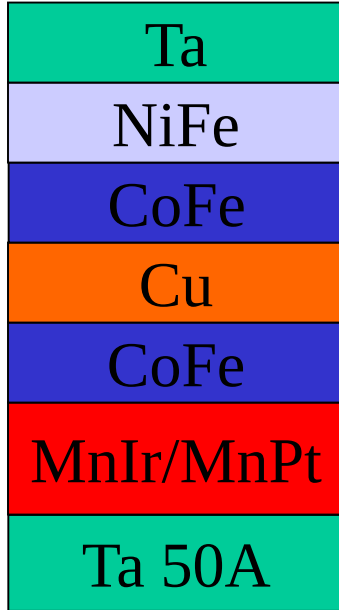


Neel Coupling



SV materials

Basic stack(94-97)



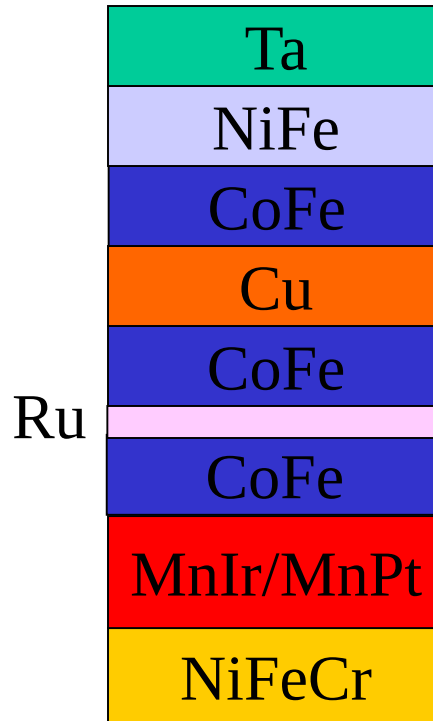
$8\% < MR < 10\%$

$H_c < 20 \text{ Oe}$

$H_f < 10 \text{ Oe}$

$Hex > 600 \text{ Oe (MnIr)}$
 $> 1000 \text{ Oe (MnPt)}$

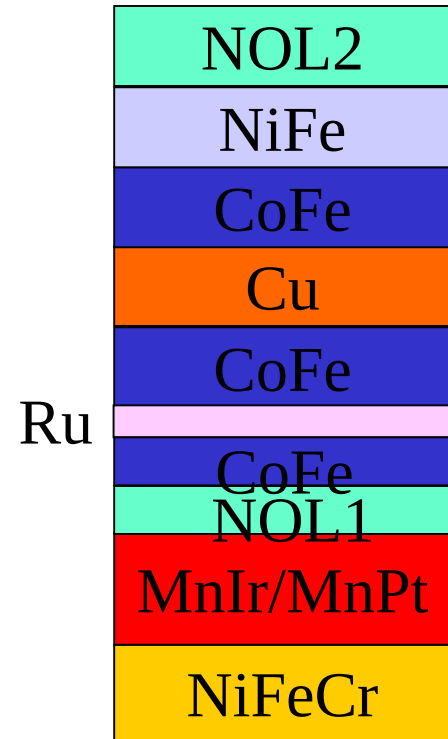
SAF+NiFeCr(97-02)



$10\% < MR < 15\%$

$Hex > 3000 \text{ Oe}$

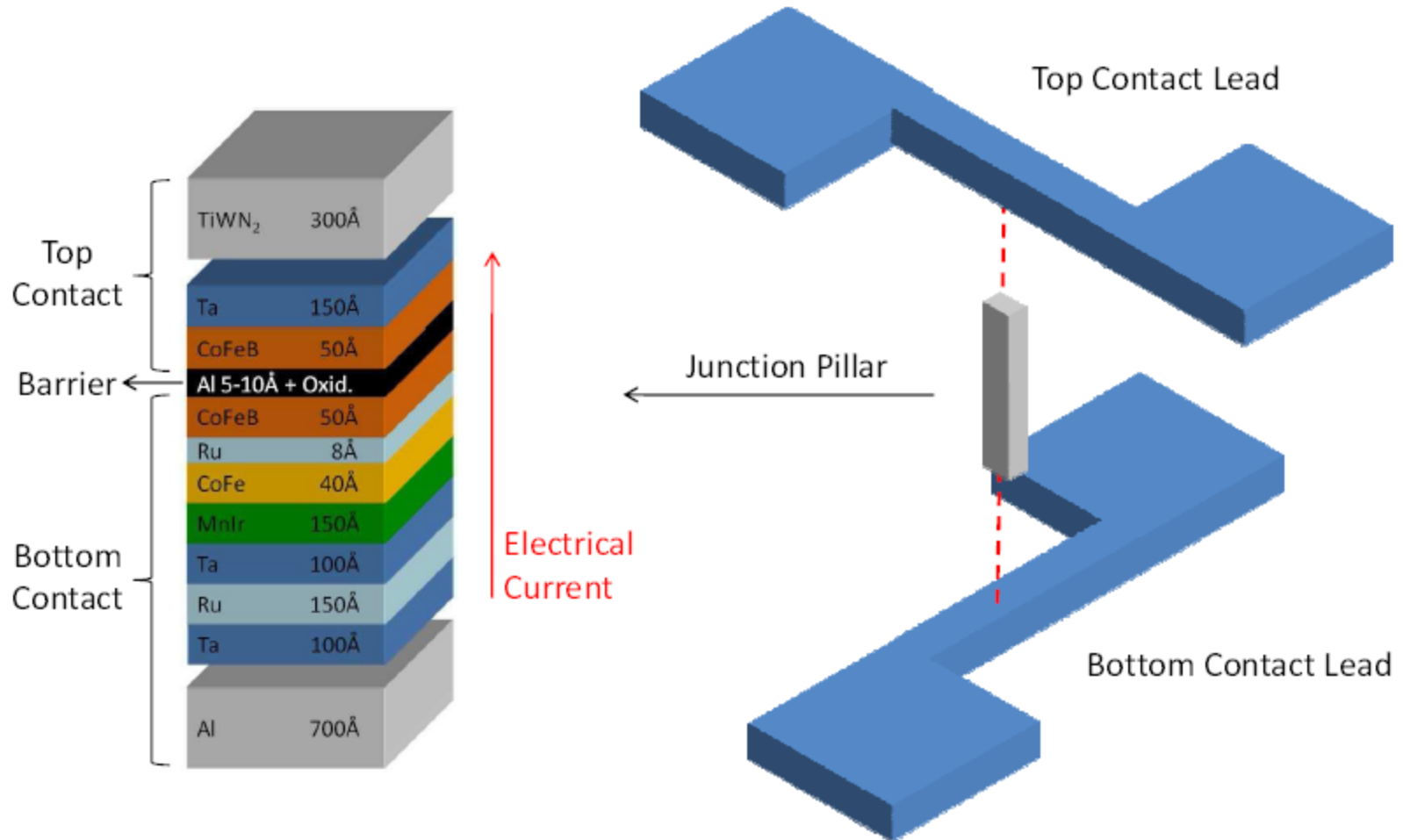
Specular SAF(01-)



$14\% < MR < 16(20)\%$

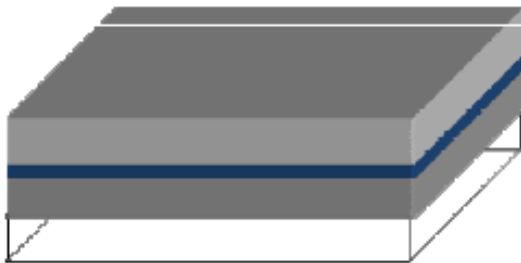
ANNEX 3: MR DEVICE MICROFABRICATION PROCESSES

Current-perpendicular-to-plane (CPP) device fabrication



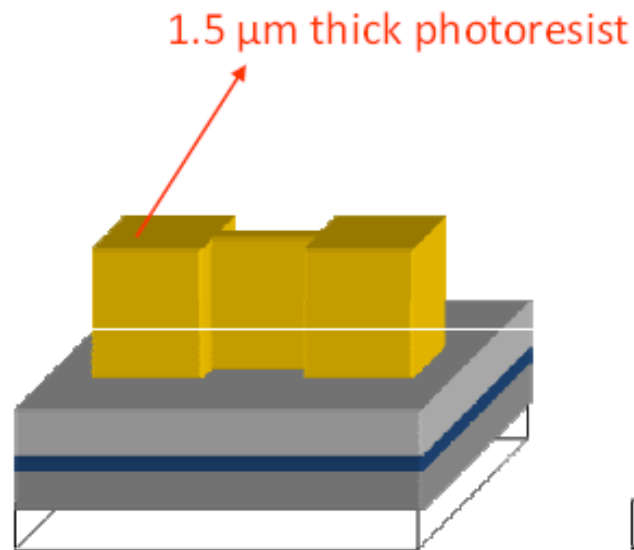
Microfabrication process

1) Deposition of the MTJ Stack

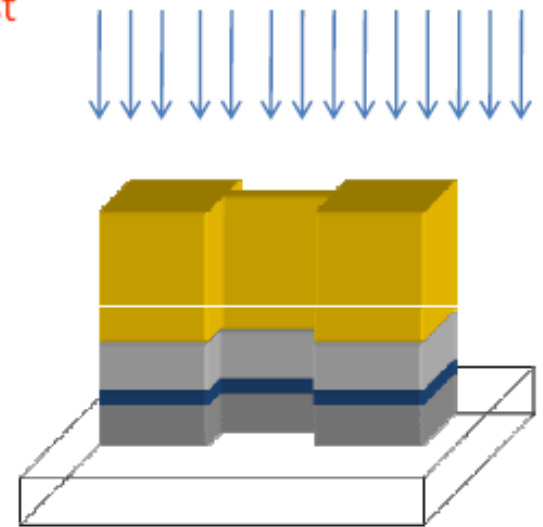


The complete stack is
~1800Å thick

2) 1st. Lithography



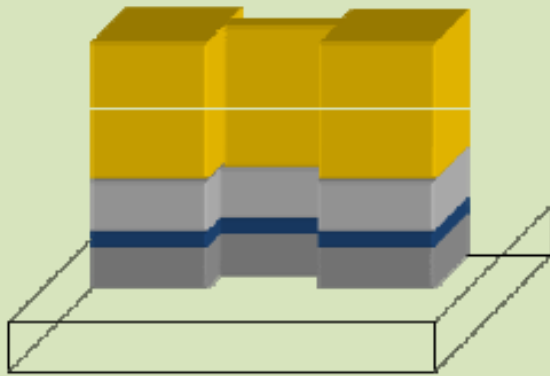
3) Ion Beam Milling



Stop point is signaled
by the transparency of
the substrate

4) Resist Strip

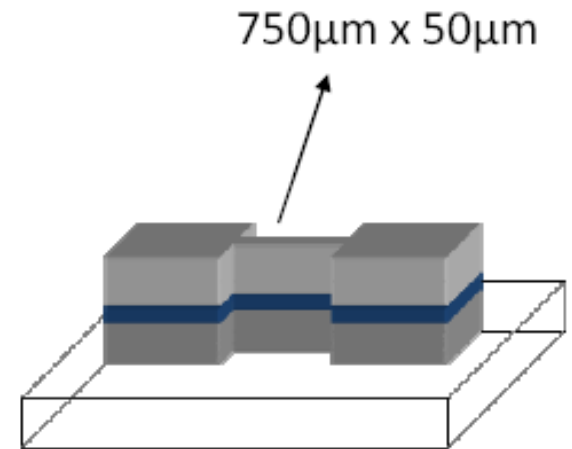
Resist Striper



Microstrip 2001 (Fuji) is used to remove the remaining photo-resist

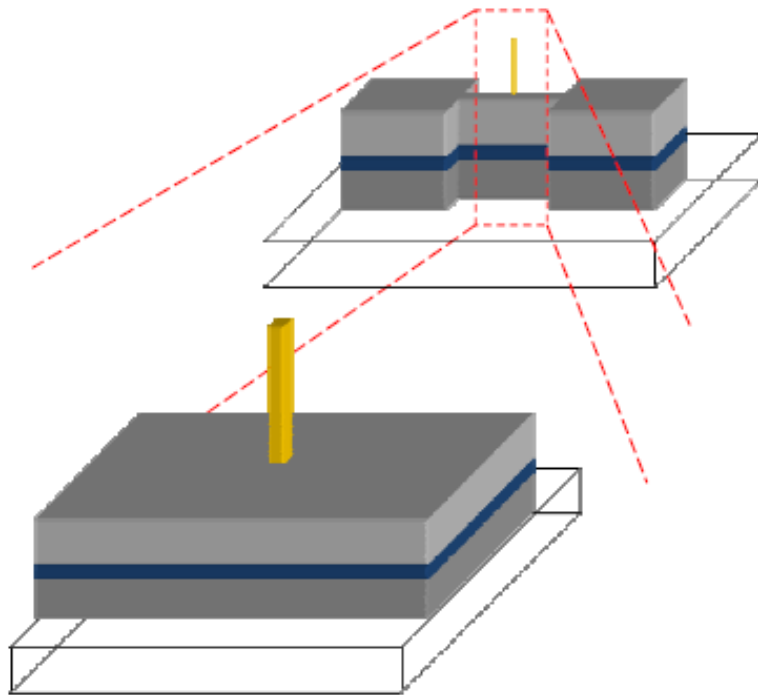


~2 hours in a hot bath (65° C) + Ultrasounds



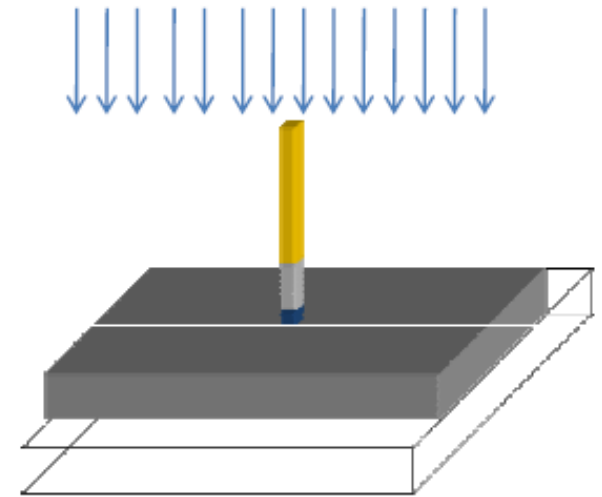
At this point, the shape of what will become the bottom contact lead is defined.

5) 2nd. Lithography : Junction Pillar Definition

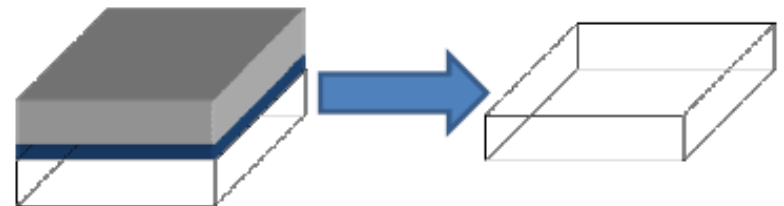


Minimum Junction Area : $1 \times 1 \mu\text{m}^2$

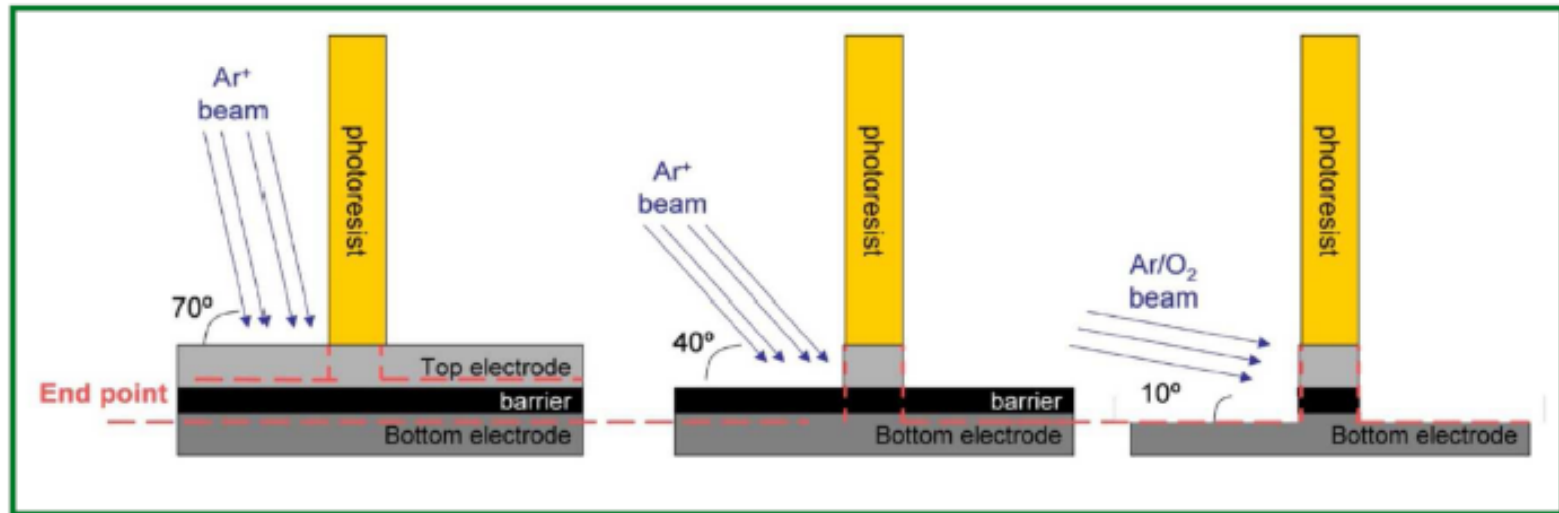
6) Junction Pillar Etching



Stop point must be after the barrier and before the substrate. Calibration samples are used to monitor the etching stop point.



6) Junction Pillar Etching



Early Etching Stage :

Large incident angle reduces shadow effects, but results in heavy redeposition

At the level of the barrier:

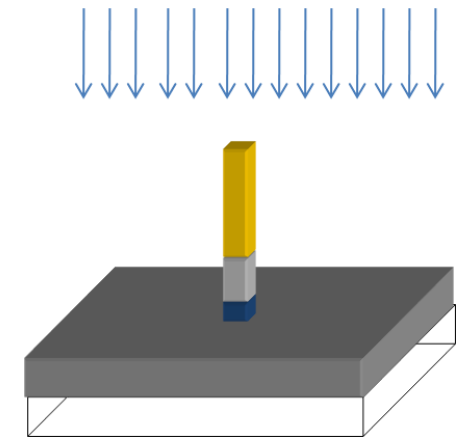
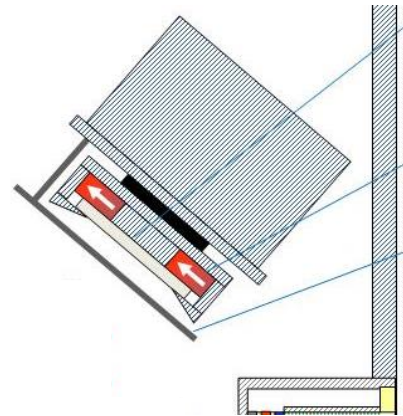
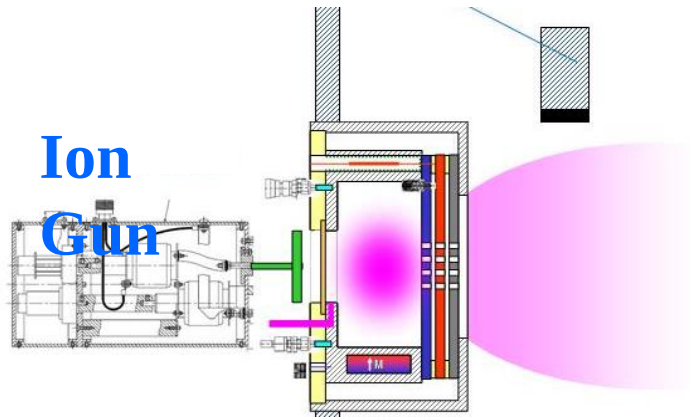
Shallow incident angle increases the etching in the sidewalls of the pillar, reducing the amount of redeposited material

Final oxidation step:

Any material deposited in the sidewalls of the junction is oxidized, becoming an insulator.

Critical Step #1 : Ion Milling of a NanoPillar

Etch Stop Point Detection



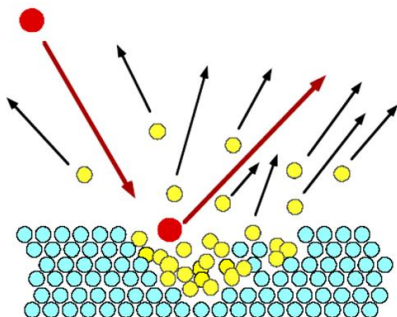
Key Parameters :

RF Power : 190W

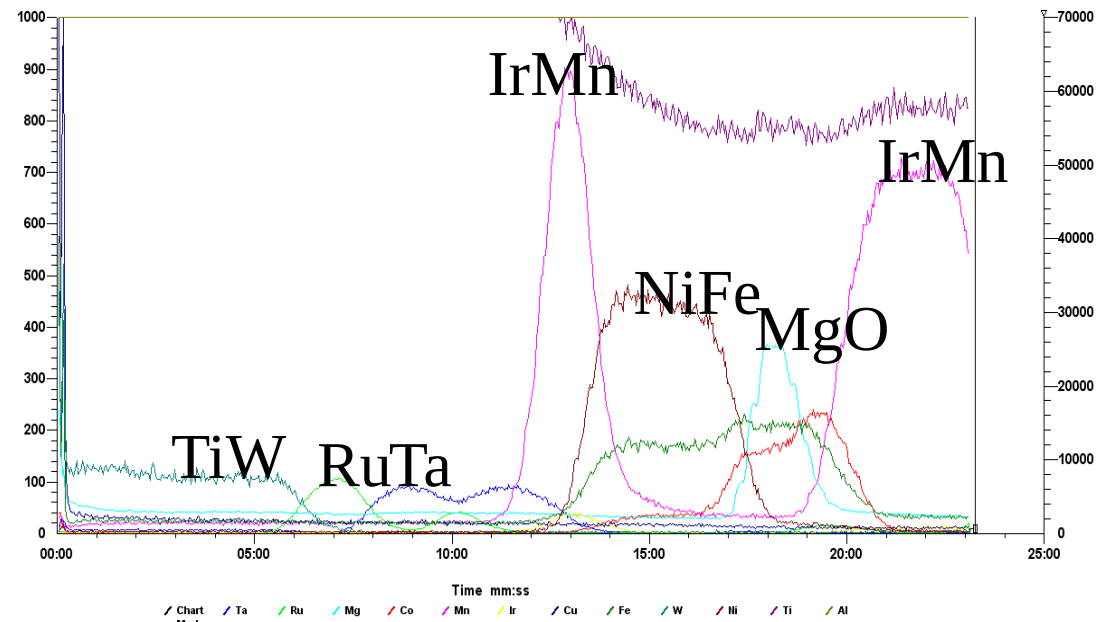
V+ : +150V

V- : -1500V

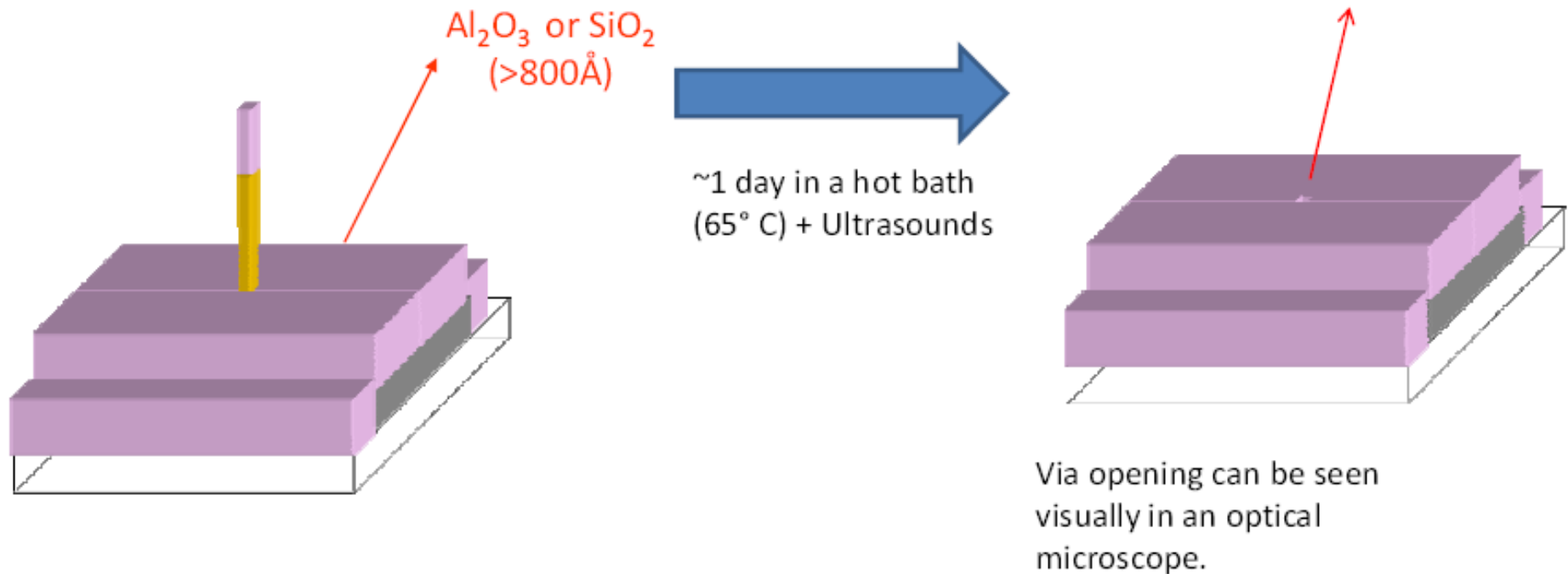
I+ : 184mA



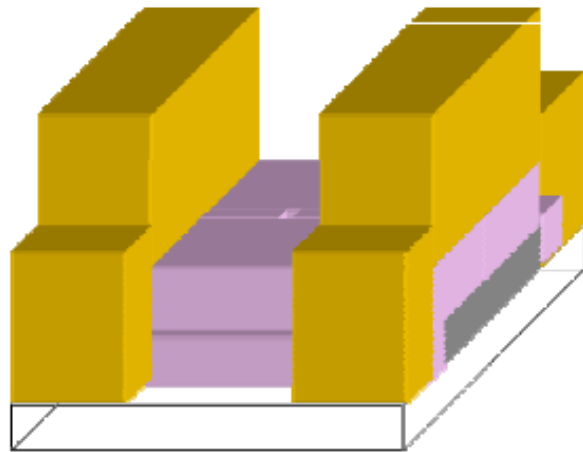
TiW	15nm
Ru	7nm
Ta	10nm
Ru	7nm
Ta	10nm
IrMn	5.5 nm
NiFe	16 nm
Ta	0.21nm
CoFeB	2.6nm
MgO	~ 1.2nm
CoFeB	2.6nm
Ru	0.85nm
CoFe	2.0nm
IrMn	20 nm
Ru	5nm
Ta	5nm
Ru	15nm
Ta	5nm
Ru	15nm
Ta	5nm



7) Insulating Oxide

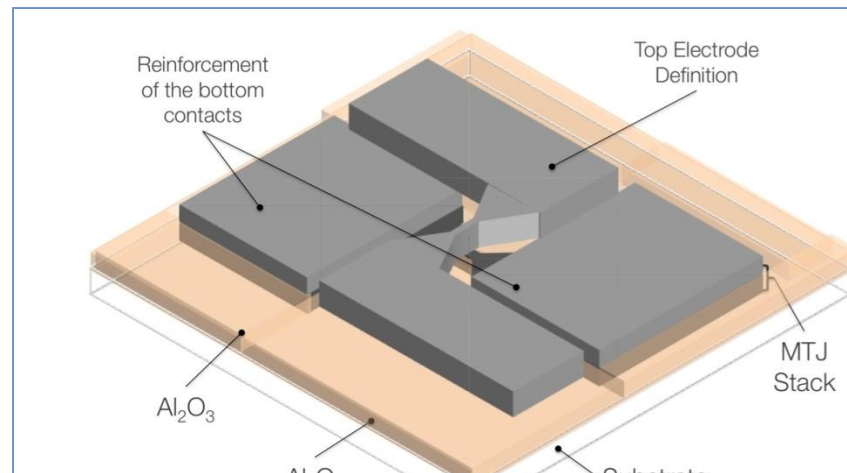
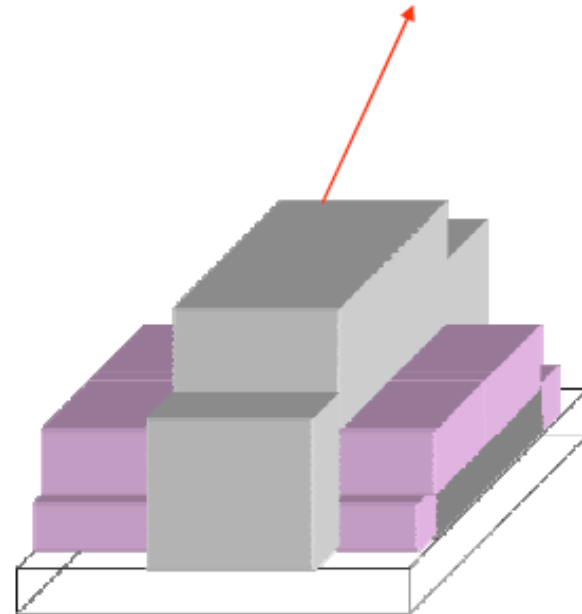


9) 3rd. Lithography : Top Lead Definition

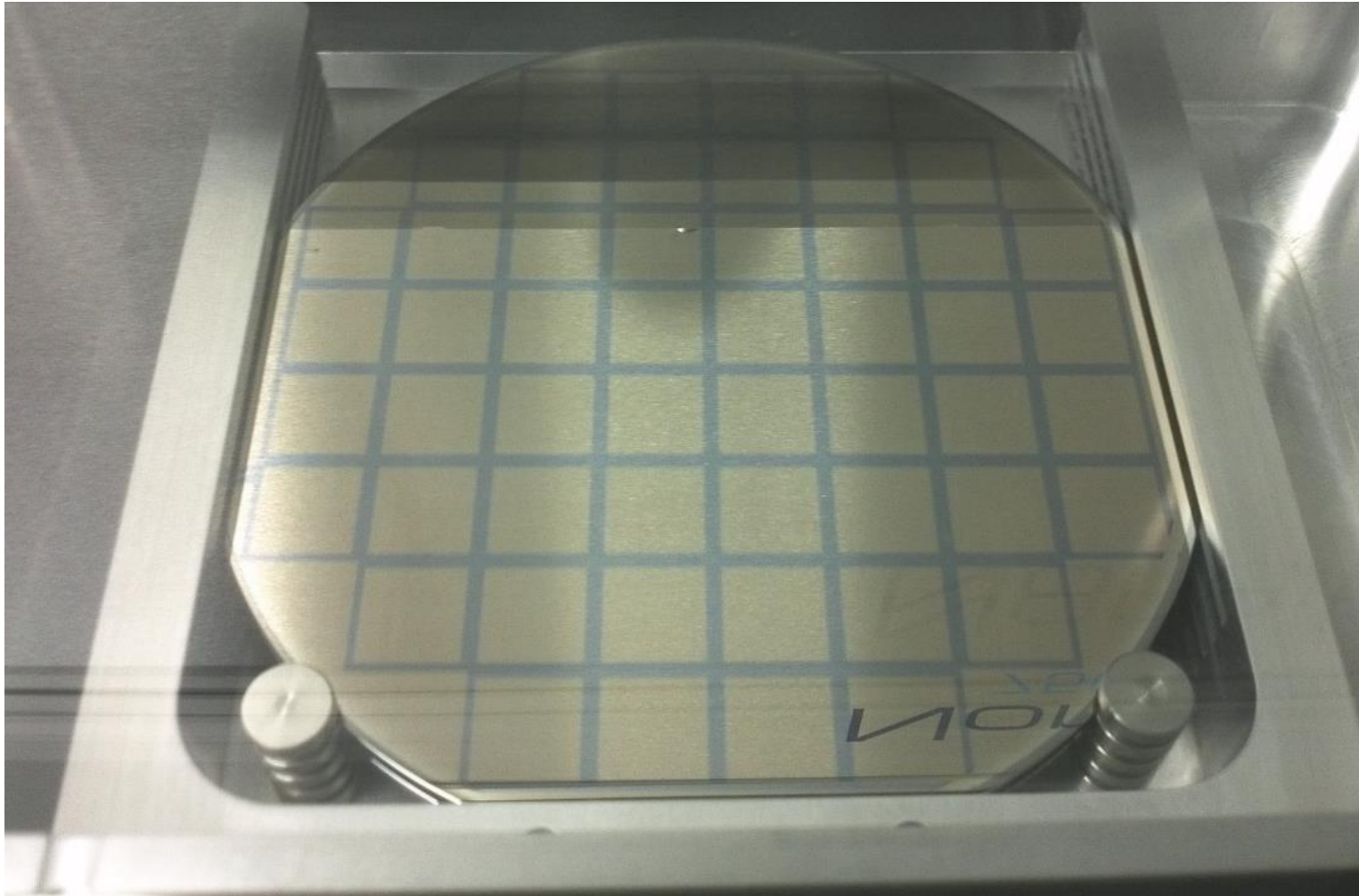


10) Top Lead Definition : Metal deposition + Lift-off

Al (3000Å) + TiWN₂ (150Å)



Up to 70,000 sensor devices in a 200mm diameter wafer

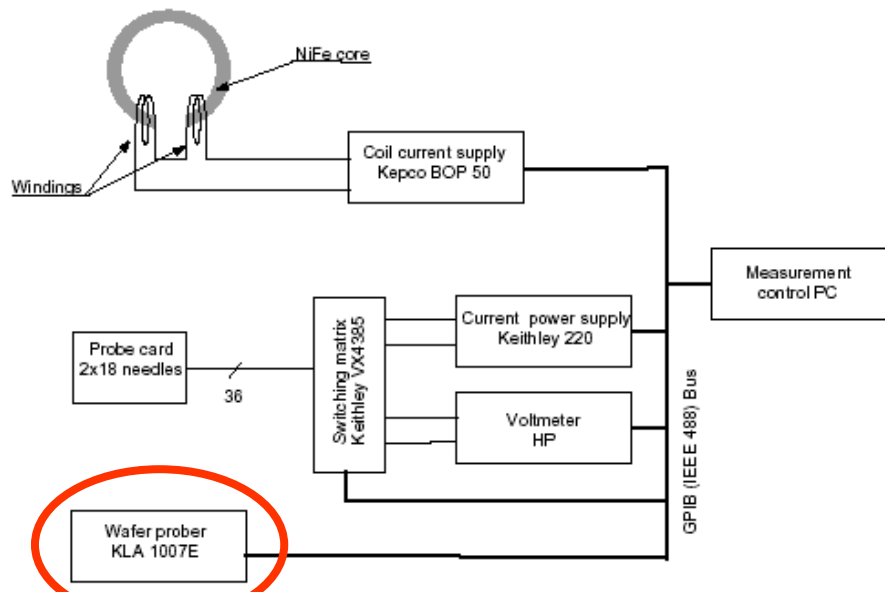


Tunnel Junctions Characterization

Automatic Measurement of Transport Properties

INESC-MN

Automatic Measurement Setup



Fully Automatic Measurement of magneto-transport properties :

- Resistance
- Magnetoresistance Transfer Curve
- Current-Voltage Characteristic
- MR Bias Voltage Dependence
- Breakdown Voltage
- Current Induced Switching

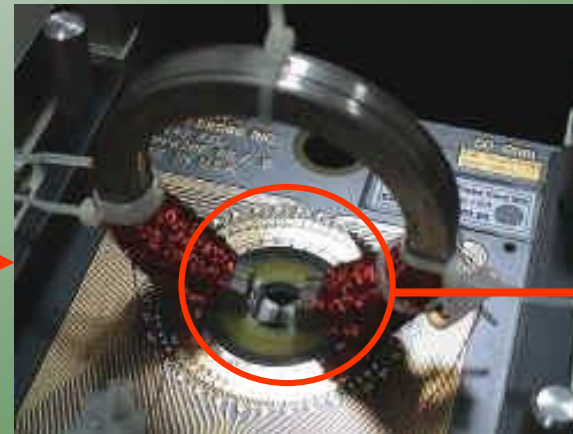
Integrated Data Analysis Software

6" Wafers measurement capability (2 or 4 contacts)

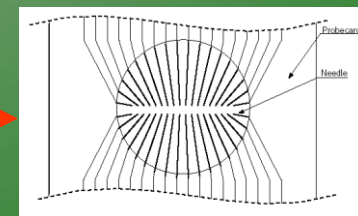
KLA 3700
Probe Station



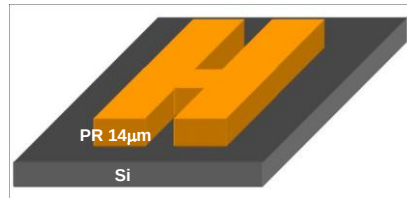
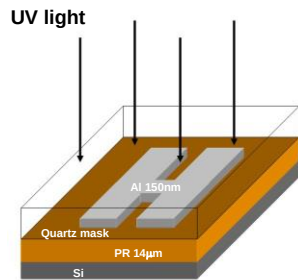
Probe Card



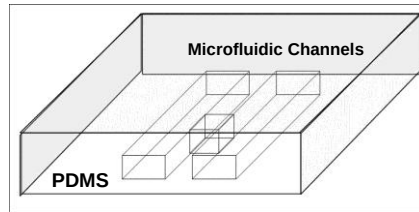
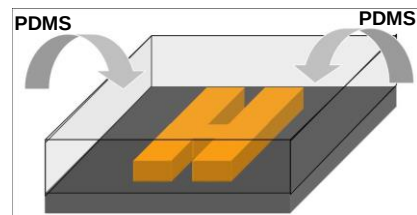
36 Kelvin
Needles



ANNEX 4: MICROFLUIDICS PROCESS

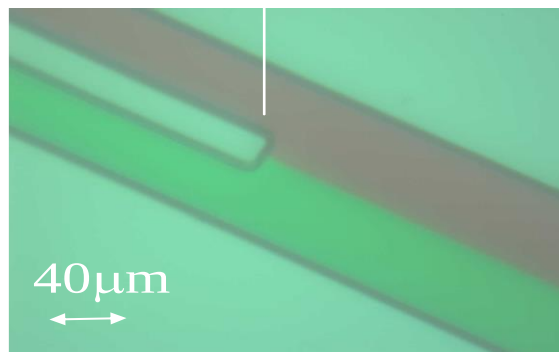


The fluidic component is made of PDMS using a standard micro molding technique.



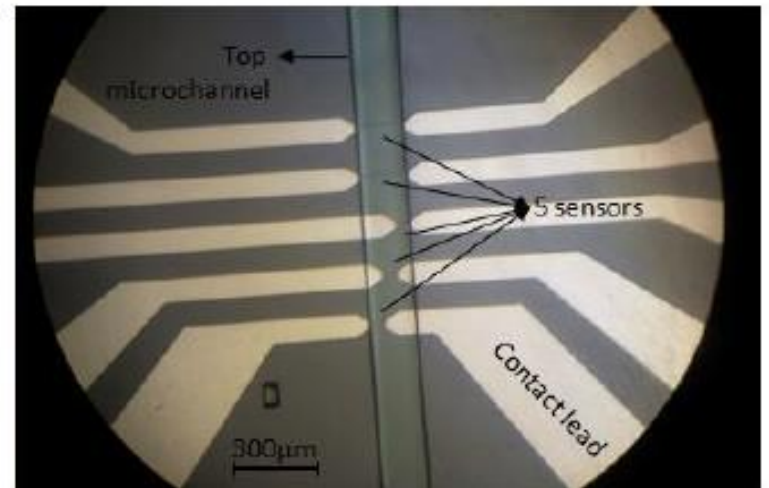
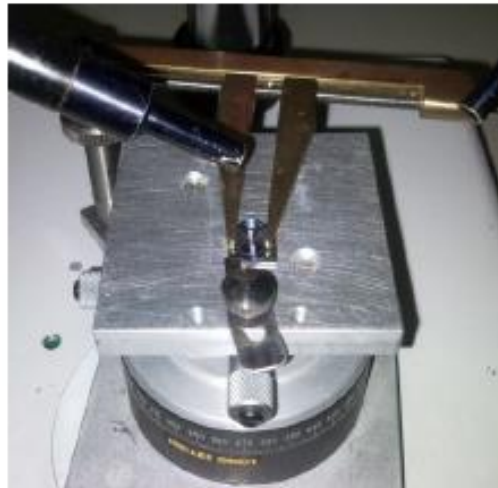
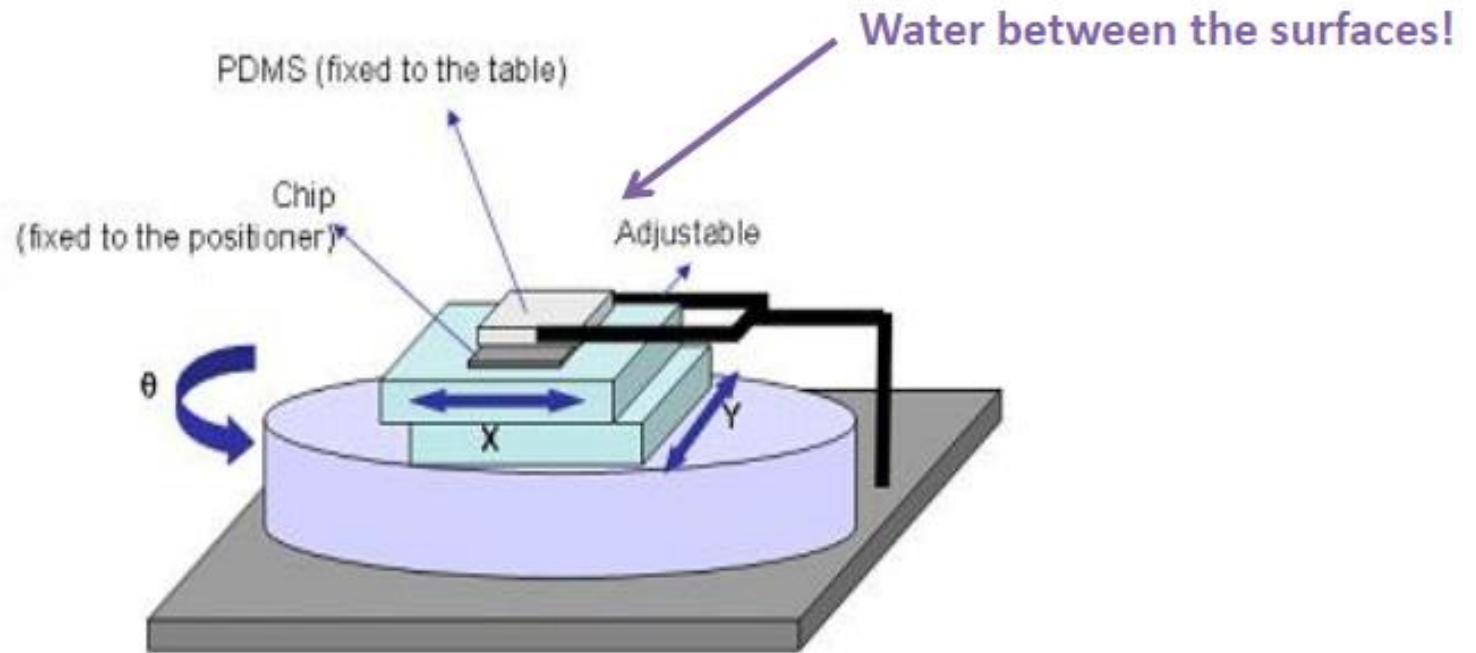
A master made of photoresist was patterned with UV lithography to define a counter mold of PDMS

Irreversible bonding between PDMS surface and the passivation surface of the chip: SiO₂

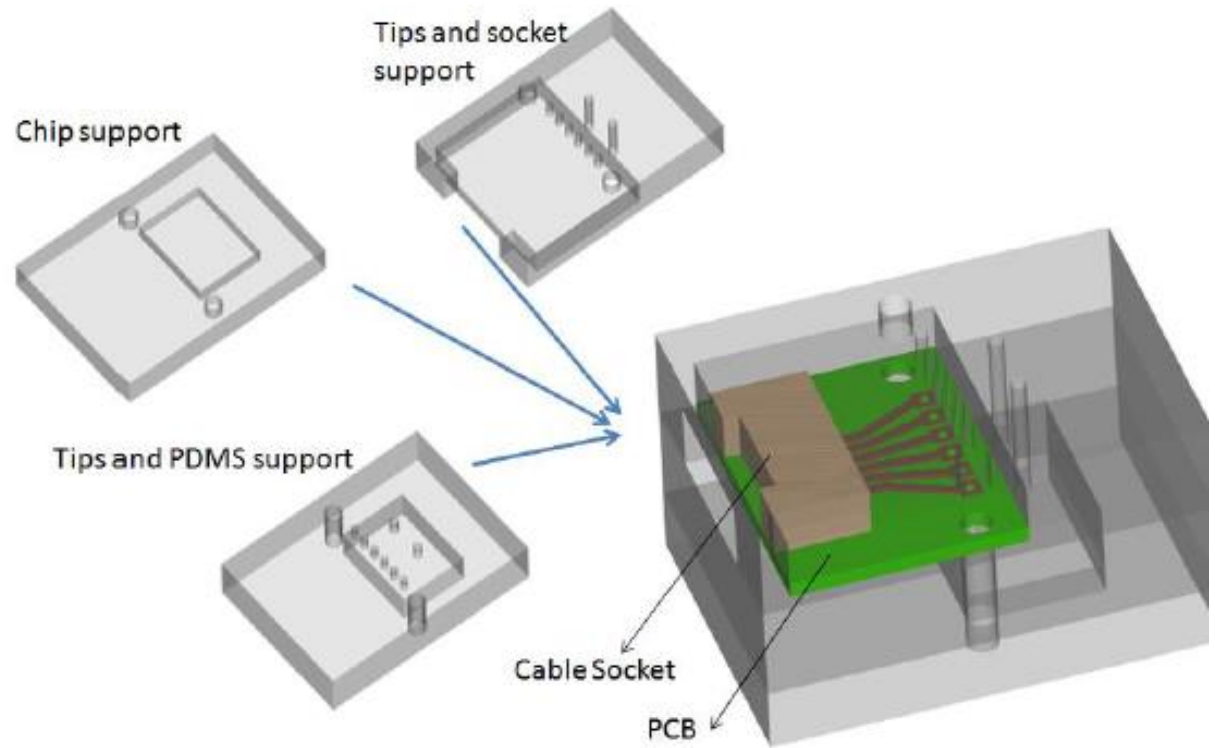
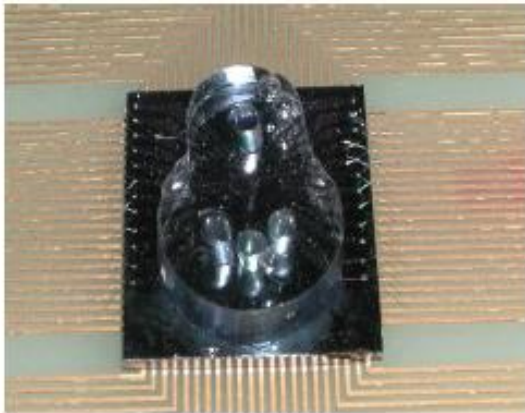


This picture shows a perfectly sealed system without leaks and with laminar flow.

Alignment



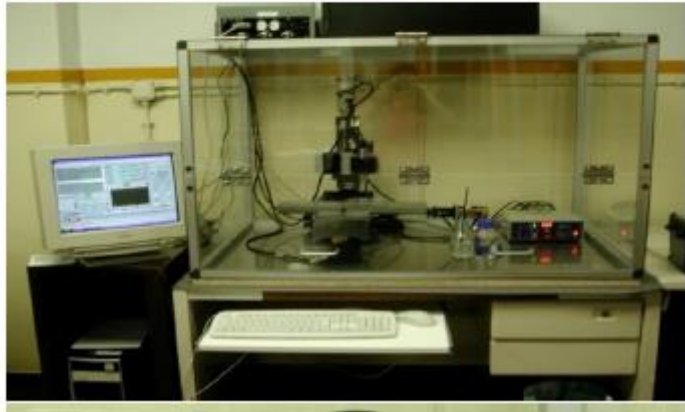
Wire bonding or packaging



ANNEX 4

Microfluidic PDMS processing

Microfluidic process development: - Macro mold (PMMA)



Milling machine



Consumables

- PDMS mold

Mixture 1:10 ratio

Degasification step

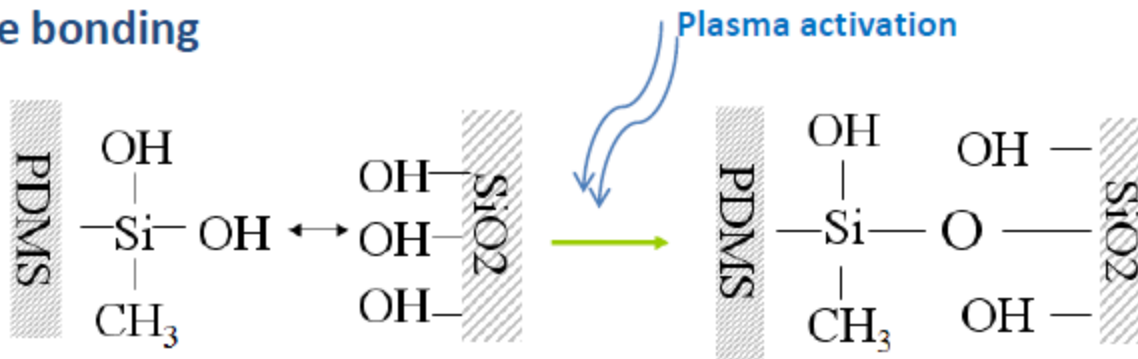
Injection into the mold



Irreversible surface bonding - II

SiO₂ - PDMS

- Irreversible bonding



Pre-cleaning protocols (SiO₂)

Machine	Plasma Conditions	Time	Contact Angle
LAM Rainbow	408 mW/cm ² , 275mTorr, 20 sccm O ₂ (oxygen plasma)	150 seconds	<5°
UVO cleaner	28mW/cm ² , 5mm separation from the UV light (ozone plasma)	30min+2min exhaustion step	<5°

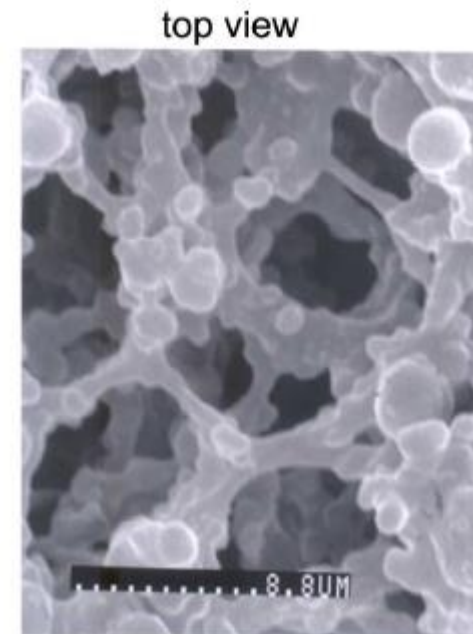
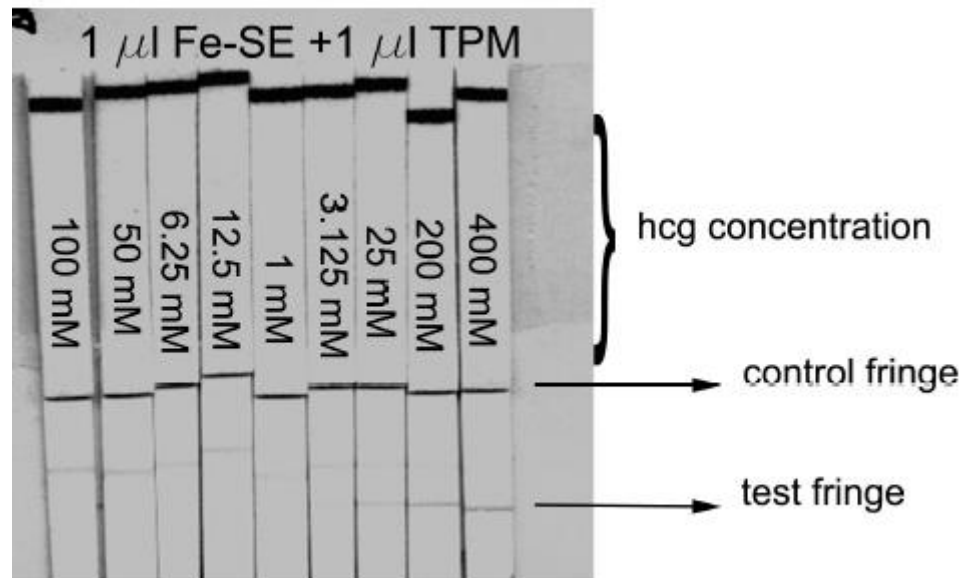
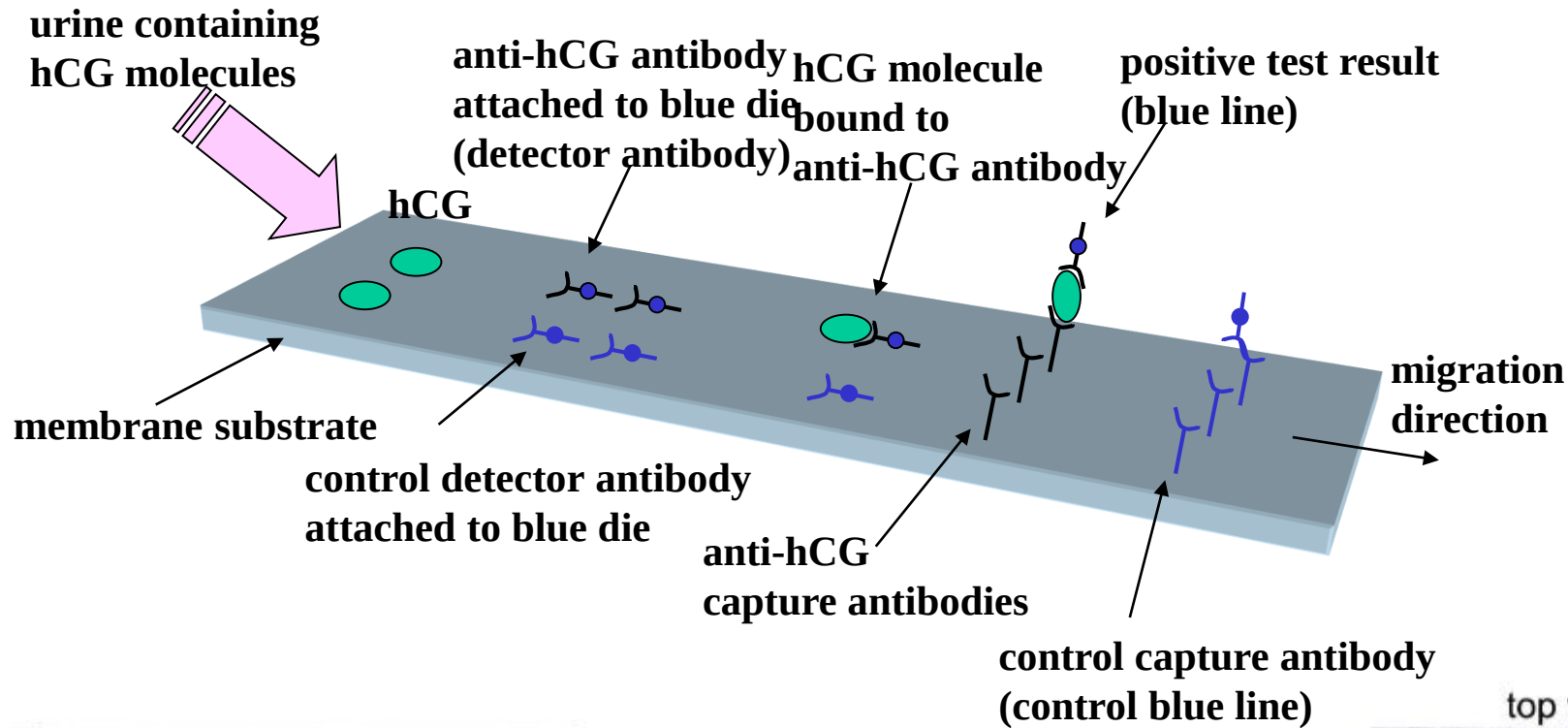
Note: the contact angle for SiO₂ not cleaned is 72.2 ± 0.20

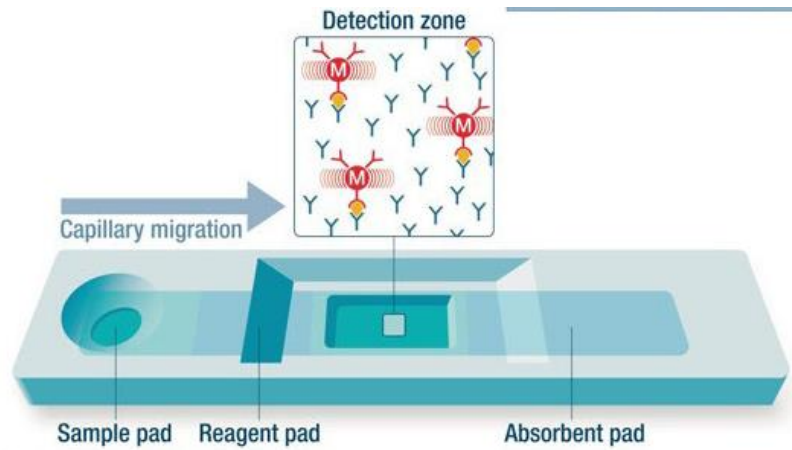


UVO Cleaner, Jelight

Other topics: 1-j) Immunocromatographic tests: also a target for MR biochips

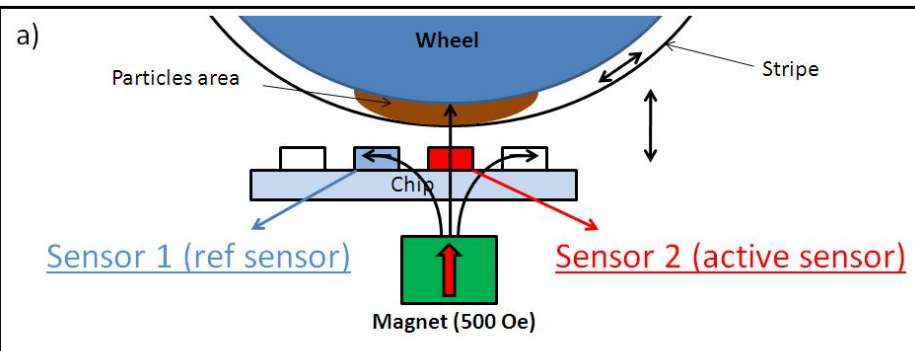
With
R.Ibarra+
de Teresa
D.Serrate
Zaragossa





Lateral Flow Membrane
Labels the analyte of interest with magnetic nanoparticles and captured by antibodies in the detection zone.

I)



II)

No moving parts.....

